

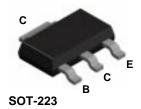
### 2N3904



### **MMBT3904**



### **PZT3904**



## **NPN General Purpose Amplifier**

This device is designed as a general purpose amplifier and switch. The useful dynamic range extends to 100 mA as a switch and to 100 MHz as an amplifier. Sourced from Process 23.

### **Absolute Maximum Ratings\***

TA = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	40	V
V <sub>CBO</sub>	Collector-Base Voltage	60	V
V <sub>EBO</sub>	Emitter-Base Voltage	6.0	V
I <sub>C</sub>	Collector Current - Continuous	200	mA
T <sub>J</sub> , T <sub>stg</sub>	Operating and Storage Junction Temperature Range	-55 to +150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- NOTES:

  1) These ratings are based on a maximum junction temperature of 150 degrees C.

  2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

8.0

5.0

pF

dB

Symbol	Parameter	Test Conditions	Min	Max	Units
OFF CHA	RACTERISTICS				
V <sub>(BR)CEO</sub>	Collector-Emitter Breakdown Voltage	$I_C = 1.0 \text{ mA}, I_B = 0$	40		V
V <sub>(BR)CBO</sub>	Collector-Base Breakdown Voltage	$I_C = 10 \mu\text{A}, I_E = 0$	60		V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 10  \mu A, I_C = 0$	6.0		V
I <sub>BL</sub>	Base Cutoff Current	$V_{CE} = 30 \text{ V}, V_{EB} = 0$		50	nA
I <sub>CEX</sub>	Collector Cutoff Current	V <sub>CE</sub> = 30 V. V <sub>EB</sub> = 0		50	nA
	RACTERISTICS*	I Ic = 0.1 mA	40	Γ	
ON CHAF	RACTERISTICS*				
	RACTERISTICS*  DC Current Gain	I <sub>C</sub> = 0.1 mA, V <sub>CE</sub> = 1.0 V	40		
ON CHAF		$I_C = 1.0 \text{ mA}, V_{CE} = 1.0 \text{ V}$	70		
		$I_C = 1.0 \text{ mA}, V_{CE} = 1.0 \text{ V}$ $I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$	70 100	300	
		$I_C = 1.0 \text{ mA}, V_{CE} = 1.0 \text{ V}$ $I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$ $I_C = 50 \text{ mA}, V_{CE} = 1.0 \text{ V}$	70 100 60	300	
h <sub>FE</sub>		$I_C = 1.0 \text{ mA}, V_{CE} = 1.0 \text{ V}$ $I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$	70 100	300	
h <sub>FE</sub>		$I_C = 1.0 \text{ mA}, V_{CE} = 1.0 \text{ V}$ $I_C = 10 \text{ mA}, V_{CE} = 1.0 \text{ V}$ $I_C = 50 \text{ mA}, V_{CE} = 1.0 \text{ V}$	70 100 60	300	V
	DC Current Gain	$\begin{split} I_C &= 1.0 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \\ I_C &= 10 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \\ I_C &= 50 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \\ I_C &= 100 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \end{split}$	70 100 60		V
h <sub>FE</sub>	DC Current Gain	$\begin{split} I_C &= 1.0 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \\ I_C &= 10 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \\ I_C &= 50 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \\ I_C &= 100 \text{ mA}, \ V_{CE} = 1.0 \text{ V} \\ I_C &= 100 \text{ mA}, \ I_B = 1.0 \text{ mA} \end{split}$	70 100 60	0.2	-

#### SWITCHING CHARACTERISTICS (except MMPQ3904)

Noise Figure (except MMPQ3904)

t <sub>d</sub>	Delay Time	$V_{CC} = 3.0 \text{ V}, V_{BE} = 0.5 \text{ V},$	35	ns
t <sub>r</sub>	Rise Time	$I_C = 10 \text{ mA}, I_{B1} = 1.0 \text{ mA}$	35	ns
ts	Storage Time	$V_{CC} = 3.0 \text{ V}, I_{C} = 10 \text{mA}$	200	ns
t <sub>f</sub>	Fall Time	$I_{B1} = I_{B2} = 1.0 \text{ mA}$	50	ns

 $V_{EB} = 0.5 \text{ V}, I_{C} = 0,$ 

 $I_C = 100 \mu A, V_{CE} = 5.0 V,$ 

 $R_S = 1.0 k\Omega$ , f=10 Hz to 15.7 kHz

f = 1.0 MHz

Input Capacitance

### **Spice Model**

 $C_{ibo} \\$ 

NF

NPN (Is=6.734f Xti=3 Eg=1.11 Vaf=74.03 Bf=416.4 Ne=1.259 Ise=6.734 Ikf=66.78m Xtb=1.5 Br=.7371 Nc=2 lsc=0 lkr=0 Rc=1 Cjc=3.638p Mjc=.3085 Vjc=.75 Fc=.5 Cje=4.493p Mje=.2593 Vje=.75 Tr=239.5n Tf=301.2p Itf=.4 Vtf=4 Xtf=2 Rb=10)

<sup>\*</sup>Pulse Test: Pulse Width ≤ 300 μs, Duty Cycle ≤ 2.0%

(continued)

**Thermal Characteristics** 

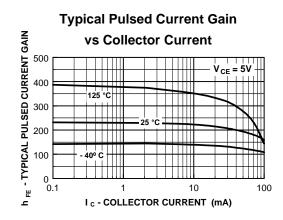
TA = 25°C unless otherwise noted

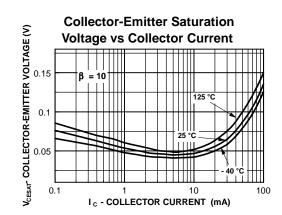
Symbol	Characteristic	Max		Units
		2N3904	*PZT3904	
$P_{D}$	Total Device Dissipation	625	1,000	mW
	Derate above 25°C	5.0	8.0	mW/°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case	83.3		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	200	125	°C/W

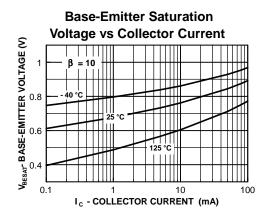
Symbol	Characteristic	Ma	Max	
		**MMBT3904	MMPQ3904	
$P_D$	Total Device Dissipation Derate above 25°C	350 2.8	1,000 8.0	mW mW/∘C
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient Effective 4 Die Each Die	357	125 240	°C/W °C/W

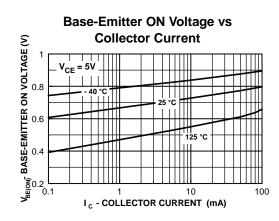
<sup>\*</sup>Device mounted on FR-4 PCB 36 mm X 18 mm X 1.5 mm; mounting pad for the collector lead min. 6 cm<sup>2</sup>.

### **Typical Characteristics**







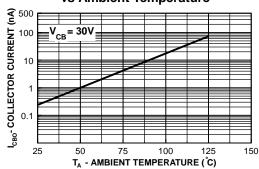


<sup>\*\*</sup>Device mounted on FR-4 PCB 1.6" X 1.6" X 0.06."

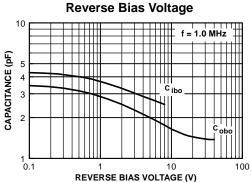
(continued)

### Typical Characteristics (continued)

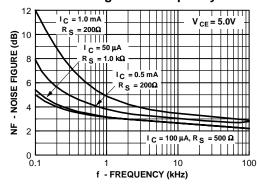




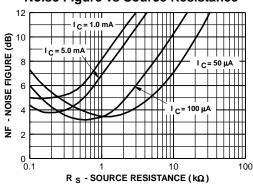
#### Capacitance vs Reverse Bias Voltage



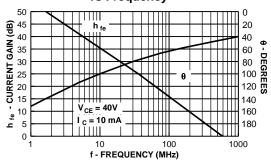
#### **Noise Figure vs Frequency**



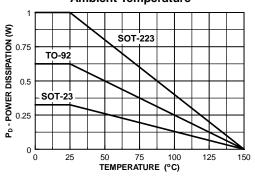
#### Noise Figure vs Source Resistance



# Current Gain and Phase Angle vs Frequency



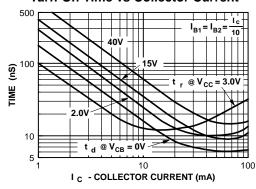
Power Dissipation vs Ambient Temperature



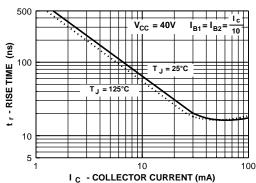
(continued)

### Typical Characteristics (continued)

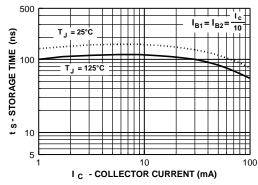




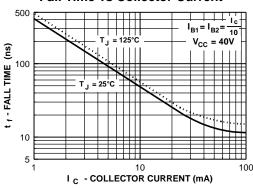
#### **Rise Time vs Collector Current**



### **Storage Time vs Collector Current**



#### **Fall Time vs Collector Current**



(continued)

### **Test Circuits**

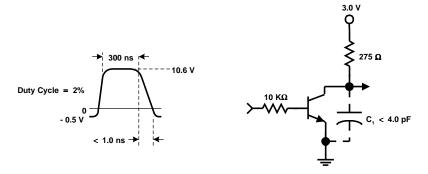


FIGURE 1: Delay and Rise Time Equivalent Test Circuit

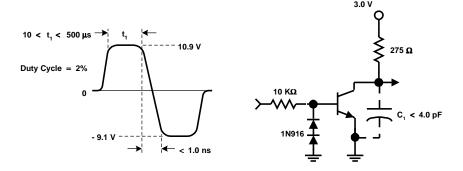


FIGURE 2: Storage and Fall Time Equivalent Test Circuit

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